Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	798531	wafer substrate	US-PGPUB; USPAT	OR	ON	2005/06/07 12:01
L2	3820	1 and ((bond$3 near3 pad) and wir$3 and (thin$6 (reduc$3 near3 thickness))and (solder near5 bump (bump near5 electrode)))	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 12:01
L3	380	2 and (shim (support$3 near10 metal))	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 12:02
L4	162	3 and ring	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 11:54
L5	1423406	wafer substrate	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 12:01
L6	121	5 and ((bond$3and pad) and wir$3 and (thin$6 (reduc$3 and thickness))and (solder and bump (bump and electrode)))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 12:01
L7	3	6 and (shim (support$3 and metal))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 12:02